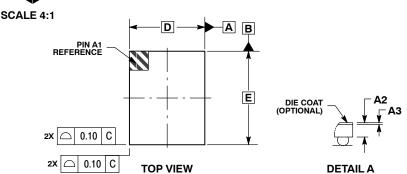
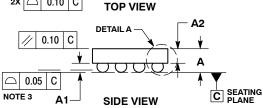
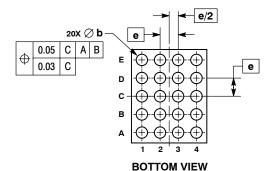


DATE 13 AUG 2013







NOTES

- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M. 1994.
- ASME 114.3M, 1994. CONTROLLING DIMENSION: MILLIMETERS. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.60	
A1	0.17	0.23	
A2	0.33	0.39	
A3	0.02	0.04	
b	0.24	0.28	
D	1.62 BSC		
E	2.02 BSC		
е	0.40 BSC		

GENERIC MARKING DIAGRAM*



= Assembly Location

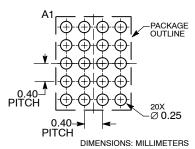
= Wafer Lot = Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP20, 1.62X2.02		PAGE 1 OF 1

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